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(54) METHOD OF JOINTING INSERTED AND MOUNTED PARTS BY REFLOW SOLDER

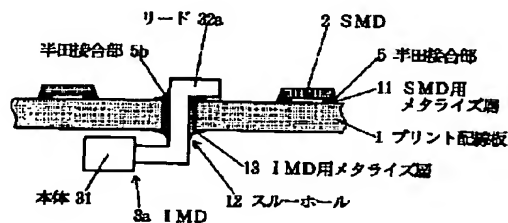
(57) Abstract:

PROBLEM TO BE SOLVED: To provide a reflow-soldering method for an IMD, which can mount the IMD at the same time with an SMD on a printed wiring board, without impairing the performance of the IMD.

SOLUTION: The lands at the tops of a metallized layer (pad) 11 for SMD at the top of a printed wiring board 1 and a metallized layer 13 for an IMD are supplied with paste solder, and the lead 32a of the IMD 3a is inserted into a through-hole 12 from the downside of the printed wiring board 1, and the tip is bent at right angle to hold the IMD 3a, and an SMD 2 is mounted on the pad 11. In this condition, it is heat-treated in a heat treating furnace, where the temperature on the side of the top is heated to a solder junction temperature and the temperature on the side of the bottom is kept at or lower than the heat resistant temperature of a body 31 of the IMD 3a. Thus, a solder junction parts

5 and 5b are formed of paste solder, and the IMD 3a and the SMD 2 are mounted on the printed wiring board 1.

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